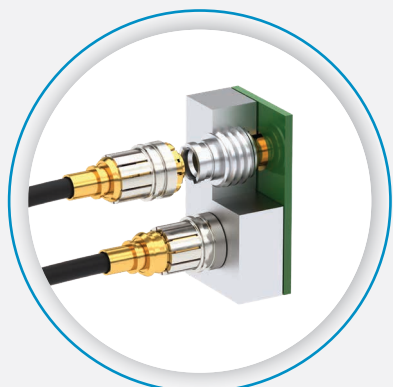


IMP FAMILY

*The New Generation of Solderless
Interconnect Solutions*



IMP-LP Hybrid



IMP-LP 40

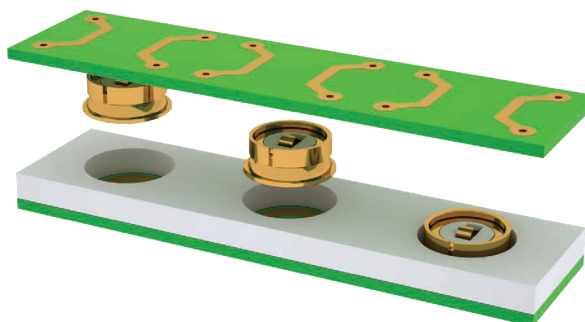


Dual IMP-LP 40

Interconnect Micro-miniature Pressure contacts are the latest innovative solution for a variety of applications, including AESA antennas. Their solderless system meets the new integration needs of board-to-board solutions.

The introduction of new antennas and radar for land, naval, air and satcom applications - including fighter jets, missiles and new generation of autonomous drones - is bringing new requirements to the market to achieve the highest performance levels.

Radiall has introduced innovative connectors to follow the trend of miniaturization of applications while increasing performance. The products provide increased integration density, lighter interconnection and simplified product structure.



Typical IMP Integration

The IMP solderless series provides a total cost savings by eliminating constraints related to soldering during installation, life cycle and maintenance. This series also facilitates the calibration of radar systems and easy integration.

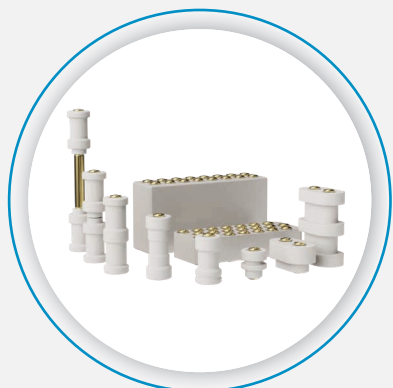
Radiall's IMP product line offers a wide range of standard and custom connectors to address all customer requests.



IMP-HD



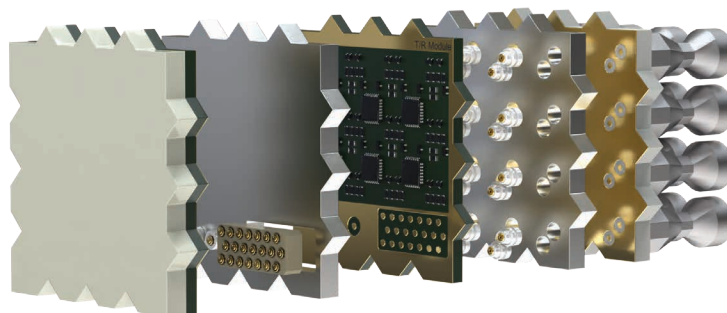
IMP-SR



IMP-SR Family

Radiall designs IMP connectors with advanced features to meet the most demanding performance requirements.

With its board-to-board interconnect innovations, Radiall reduces the interference typical with conventional solutions that can affect signal performance like phase noise. IMP connectors feature a simplified structure that divides the insertion loss by three (e.g. 0.2 dB @ 40 GHz). They can be used in applications that require high crosstalk performance. The use of solderless technology improves the reliability of interconnection by limiting the gold removal process before soldering, as gold inside the solder could generate cracks during thermal cycling.



PRODUCT	DIAMETER	FREQUENCY	B2B DISTANCE	HYBRID VERSION AVAILABLE
IMP-LP	3.9 mm	20 GHz	≥ 1.41 mm	Yes
IMP-LP 40	3.8 mm	40 GHz	≥ 3.10 mm	Yes
IMP-HD	2.8 mm	20 GHz	≥ 13.4 mm	-
IMP-SR	2.52 mm	40 GHz	≥ 3.10 mm	-

FEATURES & BENEFITS

- Up to 40 GHz
- Low phase noise: -20 to -30 dB @ 1 kHz
- Insertion loss: ≤ 0.25 dB
- Crosstalk: -85 dB typ. @ 18 GHz
- Diameter: from 2.52 mm
- Board-to-board distance: from 1.41